

TECHNICAL DOCUMENTATION

CHANGE NOTICE

Addendum to
KDB50 Disk Controller User Guide
(EK-KDB50-UG-001)

This change notice updates information in the KDB50 Disk Controller User Guide (EK-KDB50-UG-001). It supplies information regarding the KDB50 backplane I/O assembly and operating parameters.

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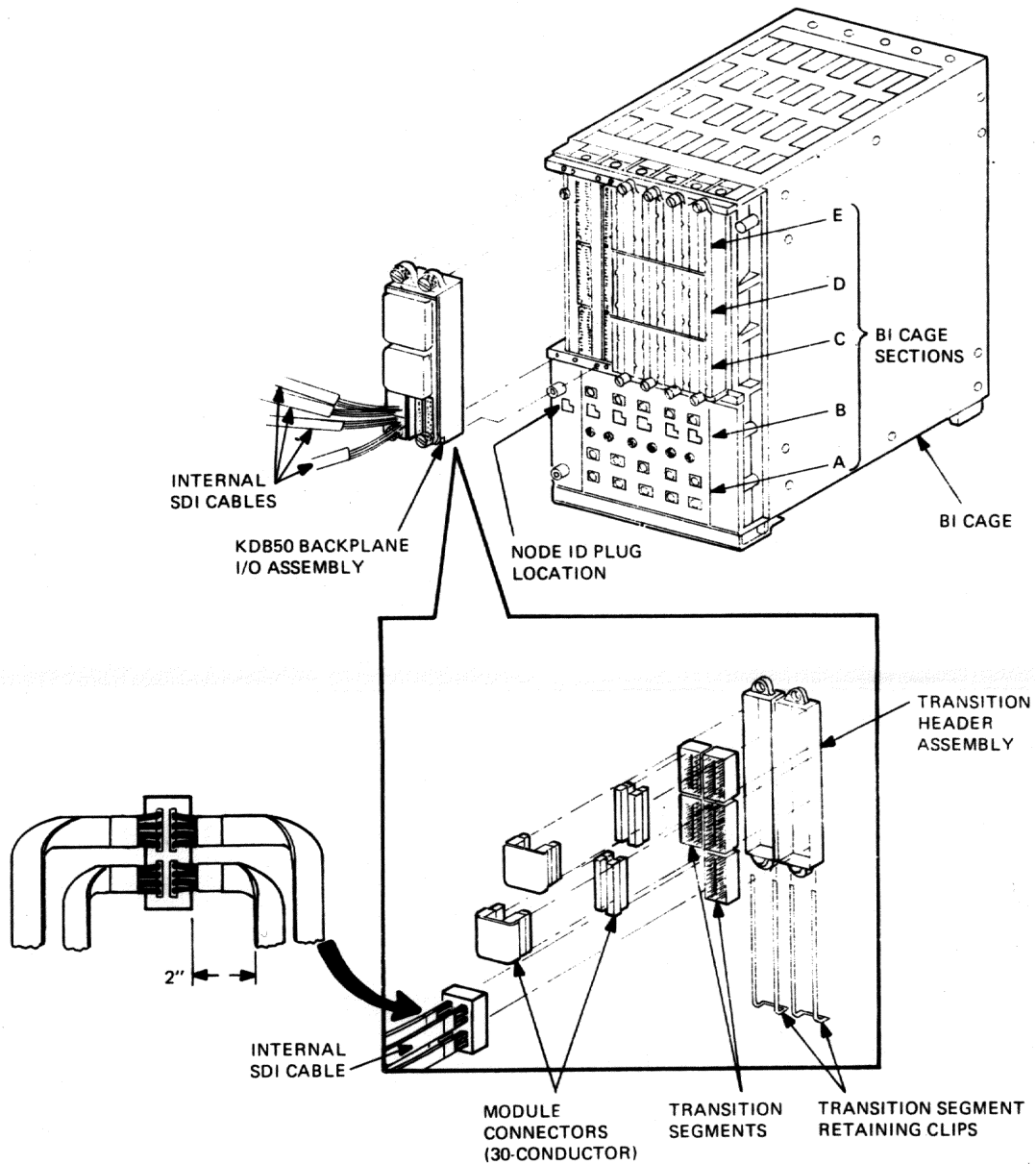
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Replace Table 1-1 in the KDB50 Disk Controller User Guide (EK-KDB50-UG-001) with the following Table 1-1.

Table 1-1: KDB50 Specifications

Characteristics	Specifications
Physical components	KDB50 processor module (T1002) KDB50 SDI module (T1003) KDB50 backplane I/O assembly 70-22492-01 (8 ft.) 70-22492-02 (15 ft.) KDB50 I/O bulkhead (74-31369-01)
Power consumption	73.6 watts nominal
Heat dissipation	Approximately 268.8 BTU/hour
Electrical voltage and current requirements	10.4 amps at +5.0 volts, 20 milliamps at +12.0 volts, 300 milliamps at -2.0 volts, 3.1 amps at -5.2 volts
Operating temperature range	10 degrees C to 40 degrees C (50 degrees F to 104 degrees F).
Operating relative humidity range	10% to 90%, with a maximum wet bulb temperature of 28 degrees C (82 degrees F) and a minimum dew point of 2 degrees C (36 degrees F)
Operating altitude range	Sea level to 2400 meters (8000 ft). Reduce the maximum allowable operating temperature by 1.8 degrees C/1000 meters (1 degree F/1000 feet) for operation above sea level
Mounting restrictions	Mounts in two BI module slots in BI cage box H9400-AA

Replace Figure 2-2 in the KDB50 Disk Controller User Guide (EK-KDB50-UG-001) with the following Figure 2-2.



NOTE: KDB50 I/O BULKHEAD ASSEMBLY POSITION IS FOR DEMONSTRATION PURPOSES ONLY

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Figure 2-2 Attaching The KDB50 Backplane I/O Assembly